



## SEMICON Europa 2022 Member Preview – November 9, 2022

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Nov 09, 2022 · By Trine Pierik · [ACM Research](#), [Amkor](#), [ASE](#), [Atotech](#), [ClassOne](#), [ERS](#), [esp](#), [ESPAT-Consulting](#), [EV Group](#), [Evatec](#), [EVG](#), [FRT](#), [Henkel](#), [KLA](#), [Onto Innovation](#), [PDF Solutions](#), [Plan Optik](#), [Plasma-Therm](#), [siemens](#), [SPTS](#), [SurplusGLOBAL](#), [trymax](#), [Veeco](#), [YES](#)



SEMICON Europa kicks off next week as microelectronics experts and visionaries gather for insights into advanced technologies that are driving industry growth and critical issues such as sustainability, mobility, healthcare, workforce development and supply chain management. We are excited to connect with our community members and industry friends and look forward to hearing the latest and greatest from our industry experts. As per usual, many of our community members will be in attendance with booths and/or delivering papers or keynotes, and Françoise will be reporting via her “Are You Listening?” podcast at Booth B1648. Here’s a quick snapshot of our member activities.

### ***Advanced Packaging Conference (APC) Speakers***

Advanced Packaging solutions require manufacturing equipment with advanced capabilities, processing of new functional materials, and manufacturing process IP developed in-house or provided by third parties. Design for reliability and design for test also needs to be part of the early design process, to shorten development time and reduce cost significantly. There is a greater need for electro-magnetic performance, thermal and thermo-mechanical simulation at the package level, or ideally a complete

virtual prototyping environment. A collaborative approach with new ideas, close co-operations, alliances, partnerships and new business models along the semiconductor supply chain is required. All these topics and more will be addressed during the APC conference.

Wednesday, November 16 | 8:30 am – 6:00 pm

ICM Munich, Room 14c

**José Silva**

Vice President of Operations & R&D, **Amkor Technology Europe Portugal**  
Amkor Activities in Portugal and Overall Trends in Europe

9:30am

**Yin Chang**

Sr. Vice President, Sales & Marketing, **ASE, Inc.**  
Advanced Packaging: Enabling a New Generation of Silicon Systems

10:35 am

**Ralf Schmidt**

R&D Manager Semiconductor, **Atotech**  
Optimization of the Cu Microstructure to Improve Cu-to-Cu Direct Bonding for 3D Integration

11:50am

**Steffen Kröhnert**

President & Founder **ESPAT-Consulting**  
Moderator Panel Discussion

Future of semiconductor manufacturing in Europe: Back –end Packaging and Test

1:20 pm

**Ramachandran Trichur**

Global Head of Semiconductor Packaging, **Henkel Corporation**  
Semiconductor Packaging Materials Enabling Advanced Flip-Chip and Heterogeneous Integration

1:50 pm

## ***Electrification & Power Semiconductors***

Wednesday, November 16 | 3:00 pm – 5:30 pm

Executive Forum, Hall B1

### ***Alex Wood***

#### **KLA Corporation (SPTS Division)**

Advances in the Field of Power Semiconductors for Next-Gen Applications

Plasma Etch & Deposition Processes for SiC Devices in Power Applications

4:10 pm

#### ***Member Booth Activities:***

ACM Research: Booth B1170 exhibiting cleaning technologies for advanced semiconductor device manufacturing.

ClassOne Technology: Visit Booth C1447 where ClassOne will showcase the latest advancements to its Solstice advanced electroplating and surface prep platform, in addition to the Trident batch processing systems.

ERS Electronic: Having introduced several new thermal management solutions to the market this year, visit Booth C1.440 to learn about the benefits of the powerful ADM330 Gen 3 thermal debond and warpage adjust machine.

FRT: Booth Party on Tuesday, Nov 15th offering traditional Kölsch beer and music from a live DJ at Booth C1533.

KLA & SPTS: Visit booth C1341 to learn more about the SensArray® in situ process monitoring and the Candela series of defect inspection systems, and Booth C1247 to learn about the SPTS wafer processing technology solutions.

#### ***Member Booth Numbers:***

ACM Research Inc.	B1170
Atotech Deutschland GmbH & Co. KG	C1165
Cimetrix Incorporated (PDF Solutions)	C1464
ClassOne Technology	C1447

ERS Electronic GmbH	C1440
EV Group (EVG)	C1211
Evatec AG	C1437
FRT GmbH	C1533
KLA Corporation (SPTS Division)	C1247
Onto Innovation	C1612
Plan Optik AG	C1241
Plasma-Therm LLC	C1755
Siemens AG	B1264
SurplusGLOBAL, Inc.	C1460
Trymax Semiconductor Equipment B.V	C1355
Veeco GmbH	C1451
Yield Engineering Systems, Inc.	B1561

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